L Number	Hits	Search Text	DB	Time stamp
11	0	6124769.pn and alumina and ruthenium	USPAT; US-PGPUB; IBM_TDB	2004/05/20 13:56
17	1	"3353124".PN.	USPAT	2004/05/20 14:12
19	6	(29/612).ccls. and ((thermistor near chip) or (chip near resistor)) and glass	USPAT; US-PGPUB; IBM_TDB	2004/05/20 15:25
25	1	(333/172).ccls. and ((thermistor near chip) or (chip near resistor)) and (alumina adj substrate) and ruthenium and stack$3	USPAT; US-PGPUB; IBM_TDB	2004/05/20 15:29
-	608	29/611.ccls.	USPAT; US-PGPUB; IBM_TDB	2003/06/04 19:12
-	586	29/$.ccls. and substrate and ((etch or etched or etching) with foil)	USPAT; US-PGPUB; IBM_TDB	2003/06/04 15:56
-	0	29/$.ccls. and (photoresistive with substrate) and ((etch or etched or etching) with foil)	USPAT; US-PGPUB; IBM_TDB	2003/06/04 15:56
-	4	29/$.ccls. and (photoresistive and substrate) and ((etch or etched or etching) with foil)	USPAT; US-PGPUB; IBM_TDB	2003/06/04 15:57
-	11	29/$.ccls. and (resistive adj (film or layer or coat or coating)) and substrate and ((etch or etched or etching) with foil)	USPAT; US-PGPUB; IBM_TDB	2003/06/04 16:03
-	17	29/$.ccls. and (resistive adj (film or layer or coat or coating)) and substrate and ((etch or etched or etching) and foil)	USPAT; US-PGPUB; IBM_TDB	2003/06/04 16:11
-	100	resistor and (resistive adj (film or layer or coat or coating)) and substrate and ((etch or etched or etching) and foil)	USPAT; US-PGPUB; IBM_TDB	2003/06/04 16:12
-	48	((method or process) with resistor) and (resistive adj (film or layer or coat or coating)) and substrate and ((etch or etched or etching) and foil)	USPAT; US-PGPUB; IBM_TDB	2003/06/04 19:49
-	7	("4336320" | "5466963" | "5849355" | "5872038" | "5935642" | "5960270" | "5994997").PN.	USPAT	2003/06/04 16:19
-	8	("4479890" | "4610810" | "4870746" | "5162144" | "5260170" | "5338567" | "5347258" | "5792594").PN.	USPAT	2003/06/04 16:30
-	28	((method or process) with resistor) and (resistive adj (film or layer or coat or coating)) and substrate and (etch or etched or etching) and foil and width	USPAT; US-PGPUB; IBM_TDB	2003/06/04 16:42
-	28	((method or process) with resistor) and (resistive adj (film or layer or coat or coating)) and substrate and (etch or etched or etching) and foil with (thick or thickness or width)	USPAT; US-PGPUB; IBM_TDB	2003/06/04 16:43
-	28	((method or process) with resistor) and (resistive adj (film or layer or coat or coating)) and substrate and (etch or etched or etching) and (foil with (thick or thickness or width))	USPAT; US-PGPUB; IBM_TDB	2003/06/04 16:48
-	32	((method or process) with resistor) and (resistive adj (film or layer or coat or coating)) and substrate and ((etch or etched or etching or polishing) with foil)	USPAT; US-PGPUB; IBM_TDB	2003/06/04 19:42

-	17	("2945180" | "3808576" | "3813631" | "4174513" | "4737747" | "4888574" | "4892776" | "5336391" | "5422313" | "5483217" | "5756971" | "5864281" | "5907273" | "5994997" | "6141870" | "6232042" | "6248612").PN.	USPAT	2003/06/04 17:03
-	14	(29/611,10.1,620).ccls. and substrate and ((etch or etched or etching) with foil) and resistor	USPAT; US-PGPUB; IBM_TDB	2003/06/05 09:15
-	38	(338/306-309).ccls. and substrate and ((etch or etched or etching) with foil) and resistor	USPAT; US-PGPUB; IBM_TDB	2003/06/05 09:16
-	3	(338/306-309).ccls. and substrate and ((etch or etched or etching) with foil) and ((method or processor assembling or making or manufacturing or step) adj resistor)	USPAT; US-PGPUB; IBM_TDB	2003/06/05 09:18
-	79	(430/313,315,324).ccls. and substrate and ((etch or etched or etching) with foil)	USPAT; US-PGPUB; IBM_TDB	2003/06/05 09:19
-	13	(430/313,315,324).ccls. and substrate and ((etch or etched or etching) with foil) and resistor	USPAT; US-PGPUB; IBM_TDB	2003/06/05 09:19
-	1	(438/462,977).ccls. and substrate and (etch or etched or etching) and foil and resistor	USPAT; US-PGPUB; IBM_TDB	2003/06/05 09:20
-	18	3669022.URPN.	USPAT	2003/06/05 10:42
-	1	6232042.URPN.	USPAT	2003/06/05 10:46
-	1	6194990.pn.	USPAT; US-PGPUB; IBM_TDB	2003/06/05 11:20
-	11	("3719508" | "4786564" | "4888574" | "4892776" | "5053318" | "5336391" | "5347258" | "5403672" | "5560812" | "5679498" | "6171921").PN.	USPAT	2003/06/05 10:48
-	11	4297670.URPN.	USPAT	2003/06/05 10:50
-	12	("2945180" | "3808576" | "3813631" | "4174513" | "4888574" | "4892776" | "5336391" | "5422313" | "5483217" | "5756971" | "5864281" | "5907273").PN.	USPAT	2003/06/05 10:51
-	3	6194990.URPN.	USPAT	2003/06/05 10:52
-	11	laminated adj resistor	USPAT; US-PGPUB; IBM_TDB	2003/06/05 11:21
-	1988	chip adj resistor	USPAT; US-PGPUB; IBM_TDB	2003/06/05 11:30
-	570	(chip adj resistor) and glass	USPAT; US-PGPUB; IBM_TDB	2003/06/05 11:22
-	328	(chip adj resistor) and glass and terminal	USPAT; US-PGPUB; IBM_TDB	2003/06/05 11:22
-	126	(chip adj resistor) and glass and terminal and nickel	USPAT; US-PGPUB; IBM_TDB	2003/06/05 11:23
-	126	(method or process or manufacturing or making or producing or steps) and (chip adj resistor) and glass and terminal and nickel	USPAT; US-PGPUB; IBM_TDB	2003/06/05 11:24
-	11	(method or process or manufacturing or making or producing or steps) adj (chip adj resistor) and glass and terminal and nickel	USPAT; US-PGPUB; IBM_TDB	2003/06/05 11:24
-	5	("3167451" | "4437140" | "4684916" | "5510594" | "5680092").PN.	USPAT	2003/06/05 11:28

-	30	(29/610.1,620,621).ccls. and (chip adj resistor)	USPAT; US-PGPUB; IBM_TDB	2003/06/05 11:39
-	10	4267634.URPN.	USPAT	2003/06/05 11:36
-	5	(29/610.1,620,621).ccls. and (chip adj resistor) and multilayer	USPAT; US-PGPUB; IBM_TDB	2003/06/05 11:40
-	11	(338/308,309,332).ccls. and (chip adj resistor) and multilayer	USPAT; US-PGPUB; IBM_TDB	2003/06/05 11:41
-	13	5170146.URPN.	USPAT	2003/06/05 11:42
-	10	5287083.URPN.	USPAT	2003/06/05 11:47
-	1	4267634.pn. and glass	USPAT; US-PGPUB; IBM_TDB	2003/06/05 13:32
-	10	4267634.URPN.	USPAT	2003/06/05 13:12
-	0	multilayered adj resistor	USPAT; US-PGPUB; IBM_TDB	2003/06/05 13:16
-	8	multi-layered near resistor	USPAT; US-PGPUB; IBM_TDB	2003/06/05 13:20
-	32723	ceramic near glass	USPAT; US-PGPUB; IBM_TDB	2003/06/05 13:20
-	3649	(ceramic near glass) and resistor	USPAT; US-PGPUB; IBM_TDB	2003/06/05 13:21
-	81	(ceramic near glass) and (chip adj resistor)	USPAT; US-PGPUB; IBM_TDB	2003/06/05 13:21
-	0	4267634.pn. and nickel	USPAT; US-PGPUB; IBM_TDB	2003/06/05 13:36
-	3612	nickel with melting	USPAT; US-PGPUB; IBM_TDB	2003/06/05 13:37
-	2226	nickel with (melting adj (point or temperature))	USPAT; US-PGPUB; IBM_TDB	2003/06/05 13:38
-	314	nickel near (melting adj (point or temperature))	USPAT; US-PGPUB; IBM_TDB	2003/06/05 13:39
-	17	nickel near (melting adj (point or temperature)) and resistor	USPAT; US-PGPUB; IBM_TDB	2003/06/05 13:50
-	9	palladium near (melting adj (point or temperature)) and resistor	USPAT; US-PGPUB; IBM_TDB	2003/06/05 13:51
-	0	(29/619).ccls. and (chip adj resistor) and multilayer	USPAT; US-PGPUB; IBM_TDB	2003/06/05 15:03
-	17	(29/611,610.1,619,620,621).ccls. and substrate and ((etch or etched or etching) with foil) and resistor	USPAT; US-PGPUB; IBM_TDB	2003/06/05 15:05
-	15	(29/610.1,619,620,621).ccls. and substrate and ((etch or etched or etching) with foil) and resistor	USPAT; US-PGPUB; IBM_TDB	2003/06/05 15:08
-	31	(174/260).ccls. and substrate and ((etch or etched or etching) with foil) and resistor	USPAT; US-PGPUB; IBM_TDB	2003/06/05 15:08
-	19	(174/260).ccls. and substrate and ((etch or etched or etching) with foil) and resistor and multilayer$3	USPAT; US-PGPUB; IBM_TDB	2003/06/05 15:09
-	2	(huber near Louis).in. and power adj chip adj resistor	USPAT; US-PGPUB; IBM_TDB	2003/11/12 17:20

-	15	"5488348"	USPAT; US-PGPUB; IBM_TDB	2004/05/18 18:05
-	1	5488348.pn.	USPAT; US-PGPUB; IBM_TDB	2004/05/18 18:11
-	0	(95/31816).CCLS.	EPO	2004/05/18 18:12
-	0	(WO95/31816).CCLS.	EPO	2004/05/18 18:12
-	0	("WO9531816").PN.	EPO	2004/05/18 18:12
-	0	(("5303115") or ("3775725") or ("4924074")).PN.	EPO	2004/05/19 13:55
-	6	(("5303115") or ("3775725") or ("4924074")).PN.	USPAT; US-PGPUB; DERWENT; IBM_TDB	2004/05/19 13:55
-	3	(("5303115") or ("3775725") or ("4924074")).PN.	USPAT; US-PGPUB; IBM_TDB	2004/05/19 13:55
-	1	("6606023").PN.	USPAT; US-PGPUB; IBM_TDB	2004/05/19 14:32
-	0	("6311390").PN.	EPO	2004/05/19 15:27
-	1	("6311390").PN.	USPAT; US-PGPUB; IBM_TDB	2004/05/19 17:16
-	5	("5488348" | "5493266" | "6020808" | "6040755" | "6157289").PN.	USPAT	2004/05/19 15:29
-	5	(thermistor adj strip) and glass	USPAT; US-PGPUB; IBM_TDB	2004/05/19 15:37
-	48	(thermistor adj chip) and glass	USPAT; US-PGPUB; IBM_TDB	2004/05/19 15:40
-	13	(thermistor adj chip) and glass and alumina	USPAT; US-PGPUB; IBM_TDB	2004/05/19 15:40
-	1	(thermistor adj chip) and glass and alumina and ruthenium	USPAT; US-PGPUB; IBM_TDB	2004/05/19 16:12
-	55	((thermistor adj chip) or (chip adj resistor)) and glass and alumina and ruthenium	USPAT; US-PGPUB; IBM_TDB	2004/05/19 16:29
-	12	((thermistor adj chip) or (chip adj resistor)) and glass and alumina and ruthenium and stack$3	USPAT; US-PGPUB; IBM_TDB	2004/05/19 16:33
-	6	((thermistor adj chip) or (chip adj resistor)) and glass and (alumina adj substrate) and ruthenium and stack$3	USPAT; US-PGPUB; IBM_TDB	2004/05/19 16:34
-	1	6311390.pn. and glass	USPAT; US-PGPUB; IBM_TDB	2004/05/19 17:16
-	0	6311390.pn. and glass and alumina	USPAT; US-PGPUB; IBM_TDB	2004/05/19 17:16
-	0	6311390.pn. and glass and ruthenium	USPAT; US-PGPUB; IBM_TDB	2004/05/19 17:17
-	1	"3353124".PN.	USPAT	2004/05/19 17:52
-	1	("6362723").PN.	USPAT; US-PGPUB; IBM_TDB	2004/05/19 18:07
-	6	((thermistor near chip) or (chip near resistor)) and glass and (alumina adj substrate) and ruthenium and stack$3	USPAT; US-PGPUB; IBM_TDB	2004/05/19 18:13

-	914	((thermistor near chip) or (chip near resistor)) and glass	USPAT; US-PGPUB; IBM_TDB	2004/05/19 18:20
-	121	((thermistor near chip) or (chip near resistor)) and glass and (alumina adj substrate)	USPAT; US-PGPUB; IBM_TDB	2004/05/19 18:12
-	33	((thermistor near chip) or (chip near resistor)) and glass and (alumina adj substrate) and ruthenium	USPAT; US-PGPUB; IBM_TDB	2004/05/19 18:25
-	77	((thermistor near chip) or (chip near resistor)) and (glass adj substrate)	USPAT; US-PGPUB; IBM_TDB	2004/05/19 18:21
-	20	((thermistor near chip) or (chip near resistor)) and glass and (alumina adj substrate) and ruthenium and plat$3	USPAT; US-PGPUB; IBM_TDB	2004/05/19 18:25
-	6	((thermistor near chip) or (chip near resistor)) and glass and (alumina adj substrate) and ruthenium and (nickel near plat$3)	USPAT; US-PGPUB; IBM_TDB	2004/05/19 18:26